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(12) United States Design Patent
Lin

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(54) **EARPHONE**

(71) Applicant: **Musong Lin**, Shenzhen (CN)

(72) Inventor: **Musong Lin**, Shenzhen (CN)

(73) Assignee: **Shenzhen Enle Industrial Co., Ltd.**, Shenzhen (CN)

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(52) **U.S. Cl.**
USPC **D14/223**

(58) **Field of Classification Search**
USPC D14/223, 205; D24/174; 128/864, 865, 128/866; 381/380, 381; 455/90.3, 575.1, 455/569.1
CPC H04R 1/10; H04R 25/00; H04R 1/105; H04R 1/1066; H04R 1/1016; H04R 5/033; H04R 5/0335; H04R 1/1091
See application file for complete search history.

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Primary Examiner — Paula Allen Greene

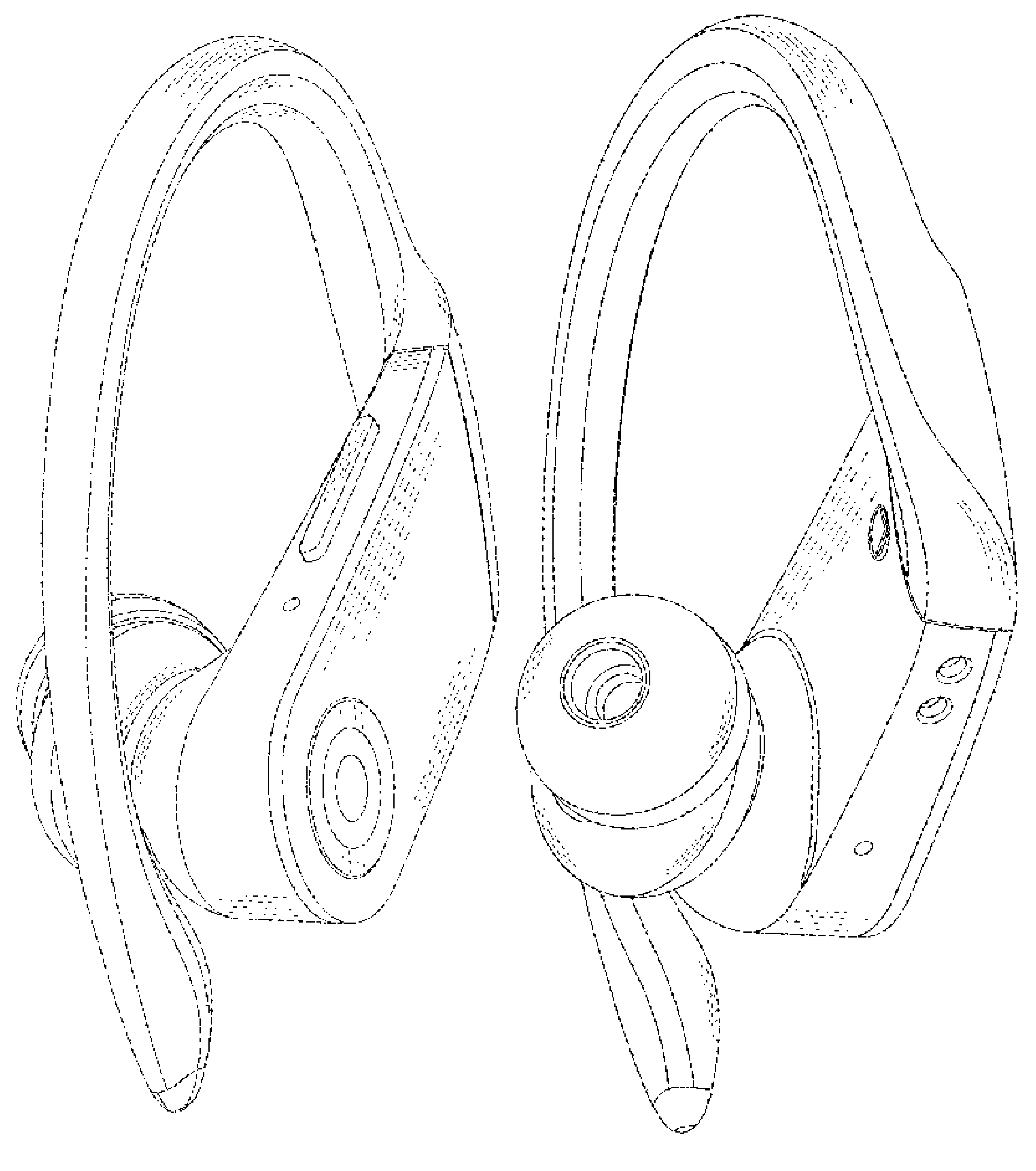
(57) **CLAIM**

The ornamental design for an earphone, as shown and described.

DESCRIPTION

FIG. **1** is a front and top perspective view of an earphone showing my new design;
FIG. **2** is a rear and bottom perspective view thereof;
FIG. **3** is a front elevation view thereof;
FIG. **4** is a rear elevation view thereof;
FIG. **5** is a top view thereof;
FIG. **6** is a bottom view thereof;
FIG. **7** is a top end view thereof; and,
FIG. **8** is a bottom end view thereof.

1 Claim, 8 Drawing Sheets



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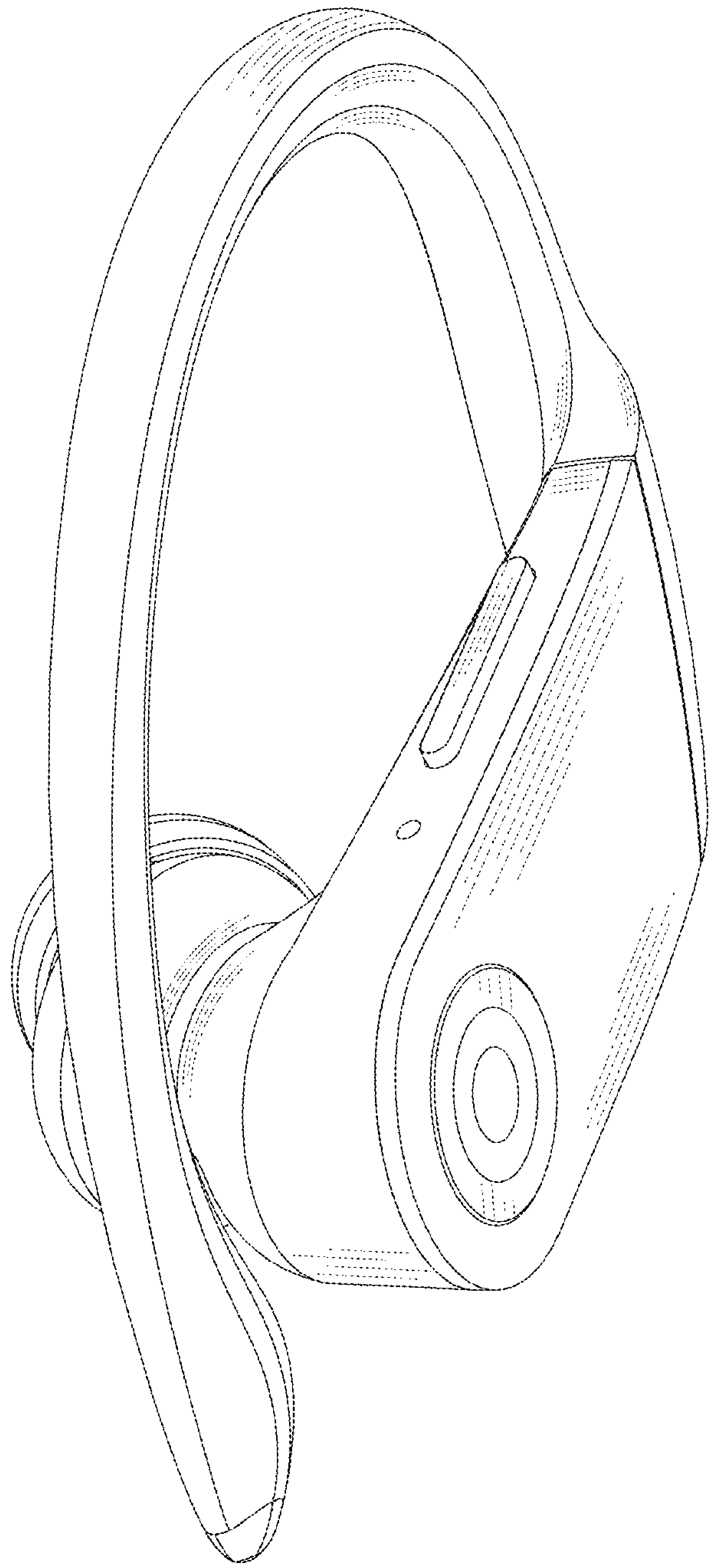

FIG.1

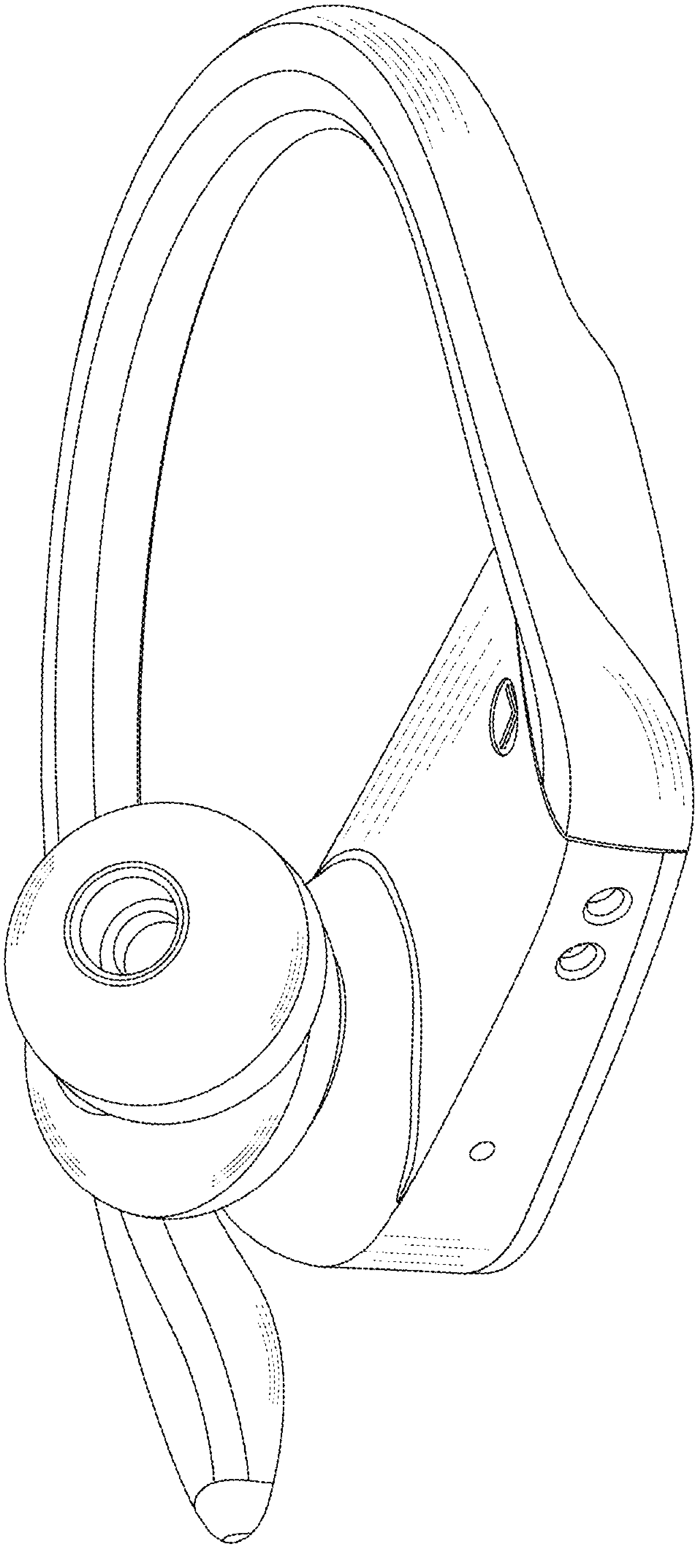

FIG.2

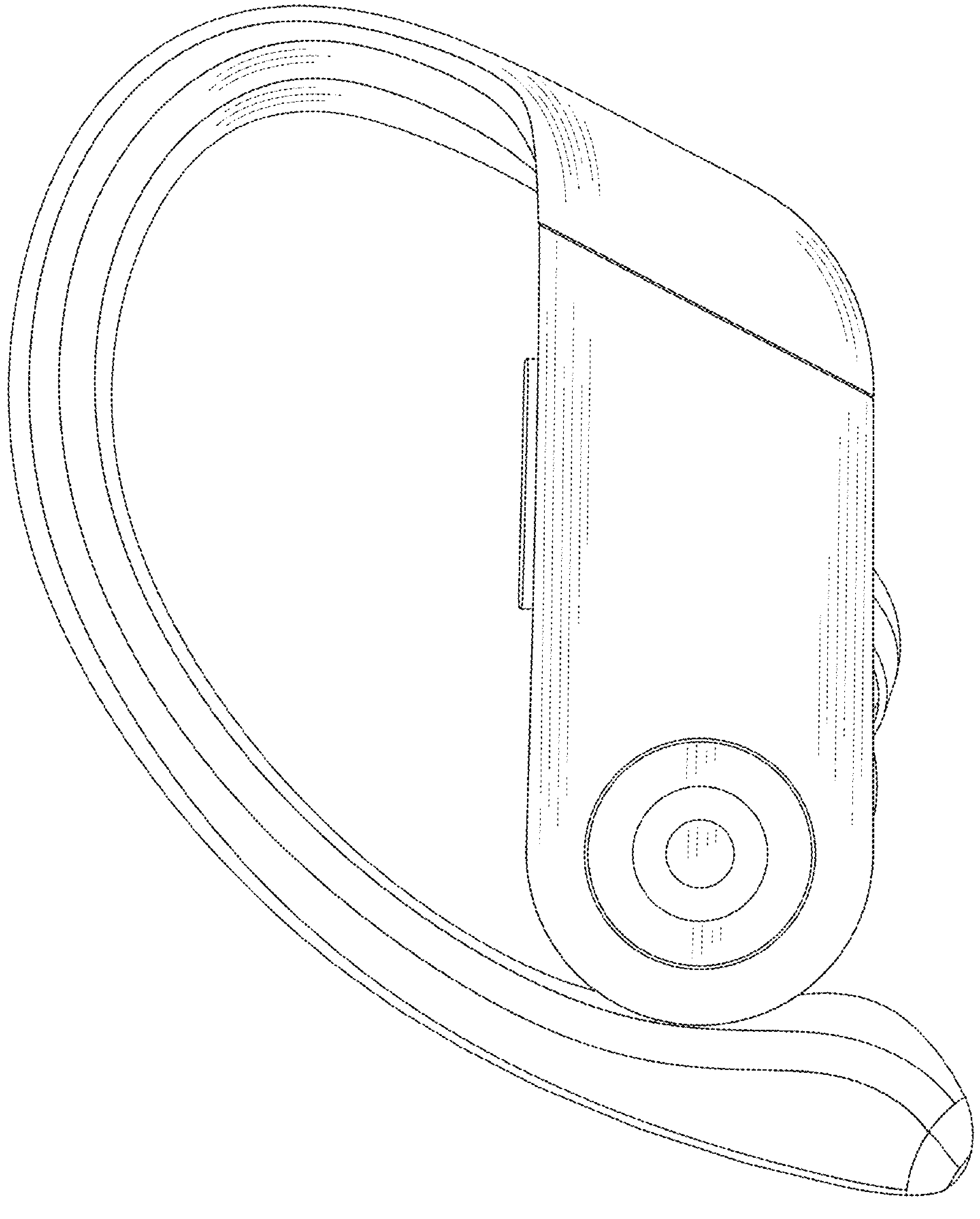

FIG.3

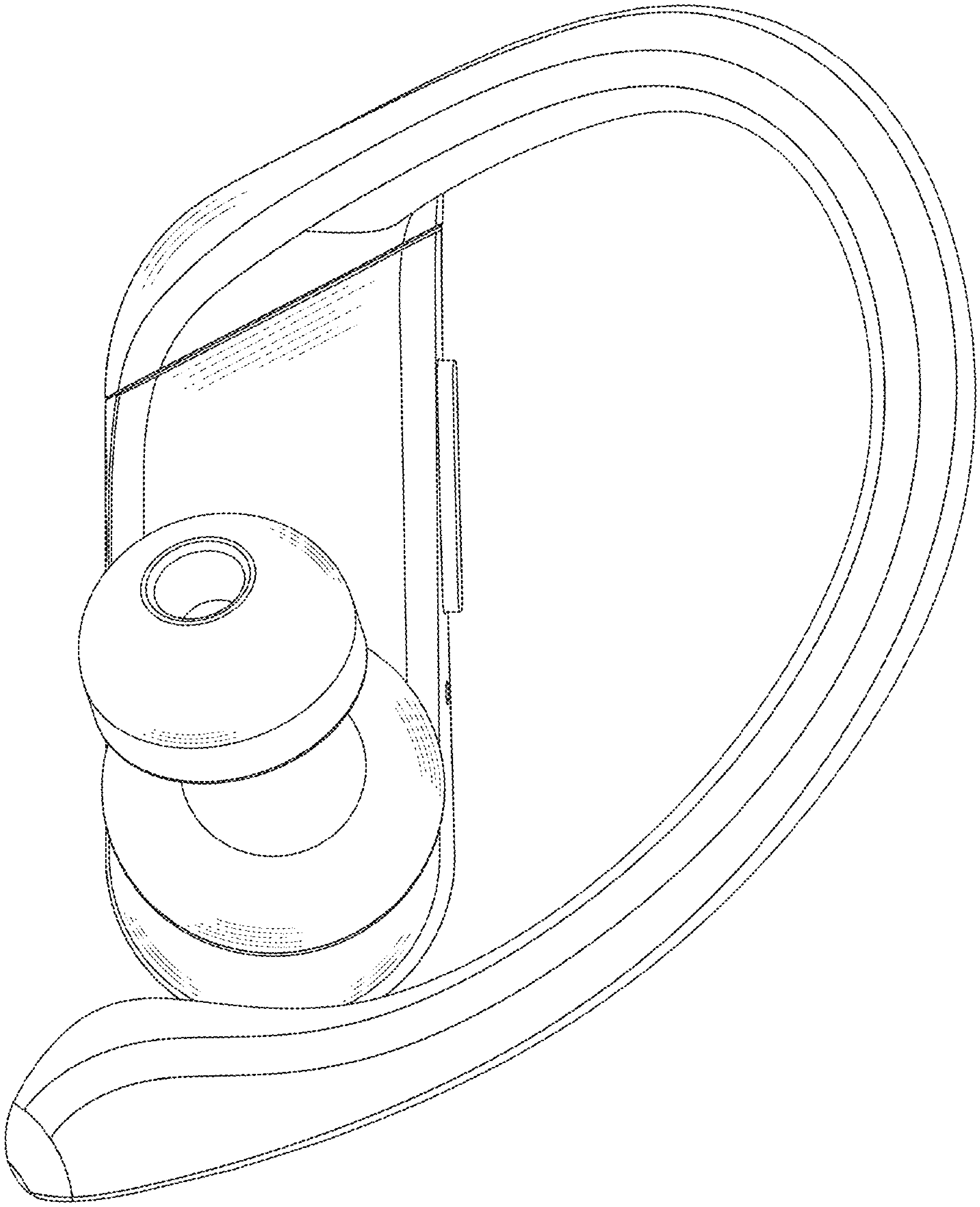

FIG.4

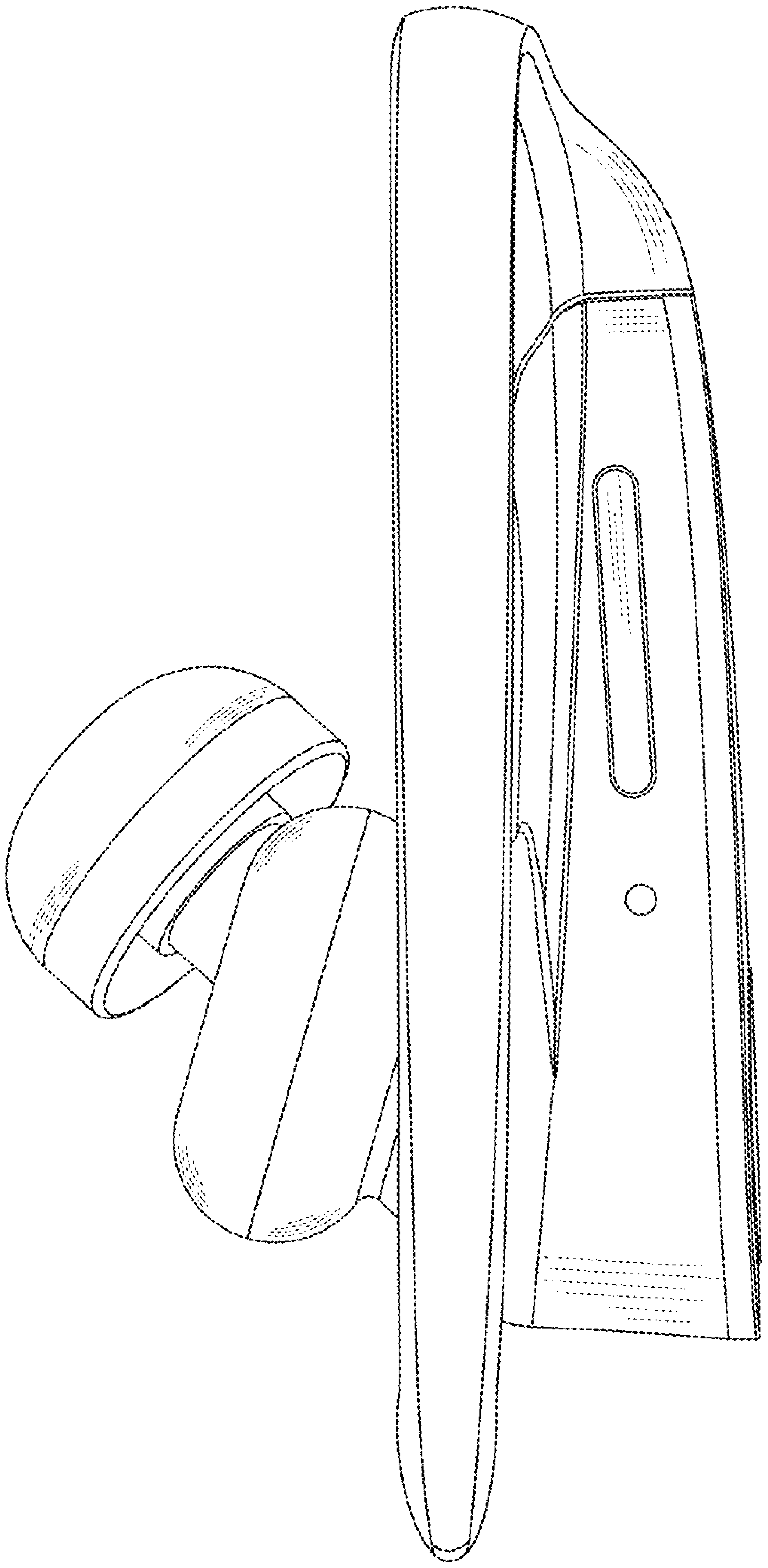

FIG. 5

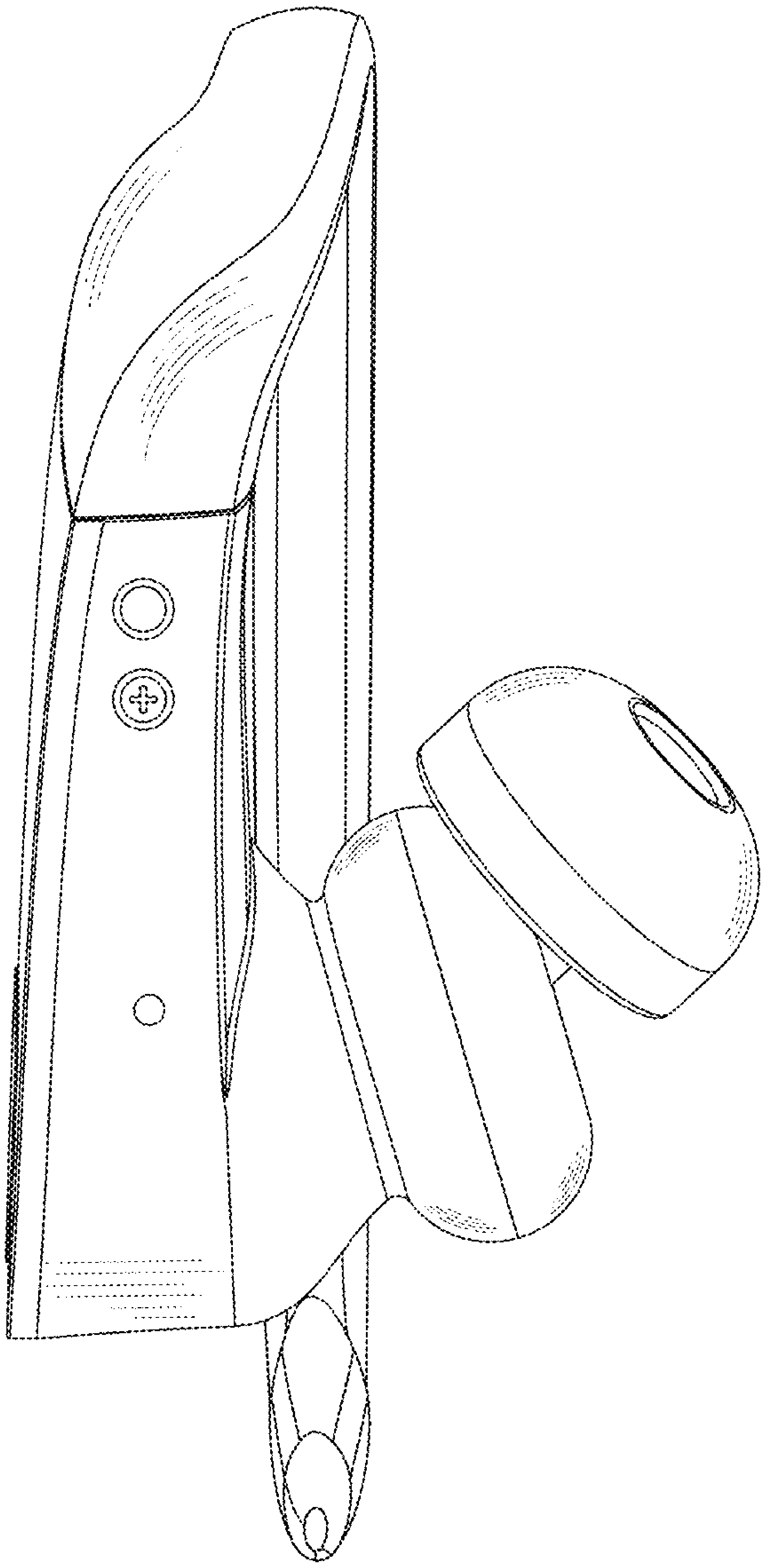

FIG. 6

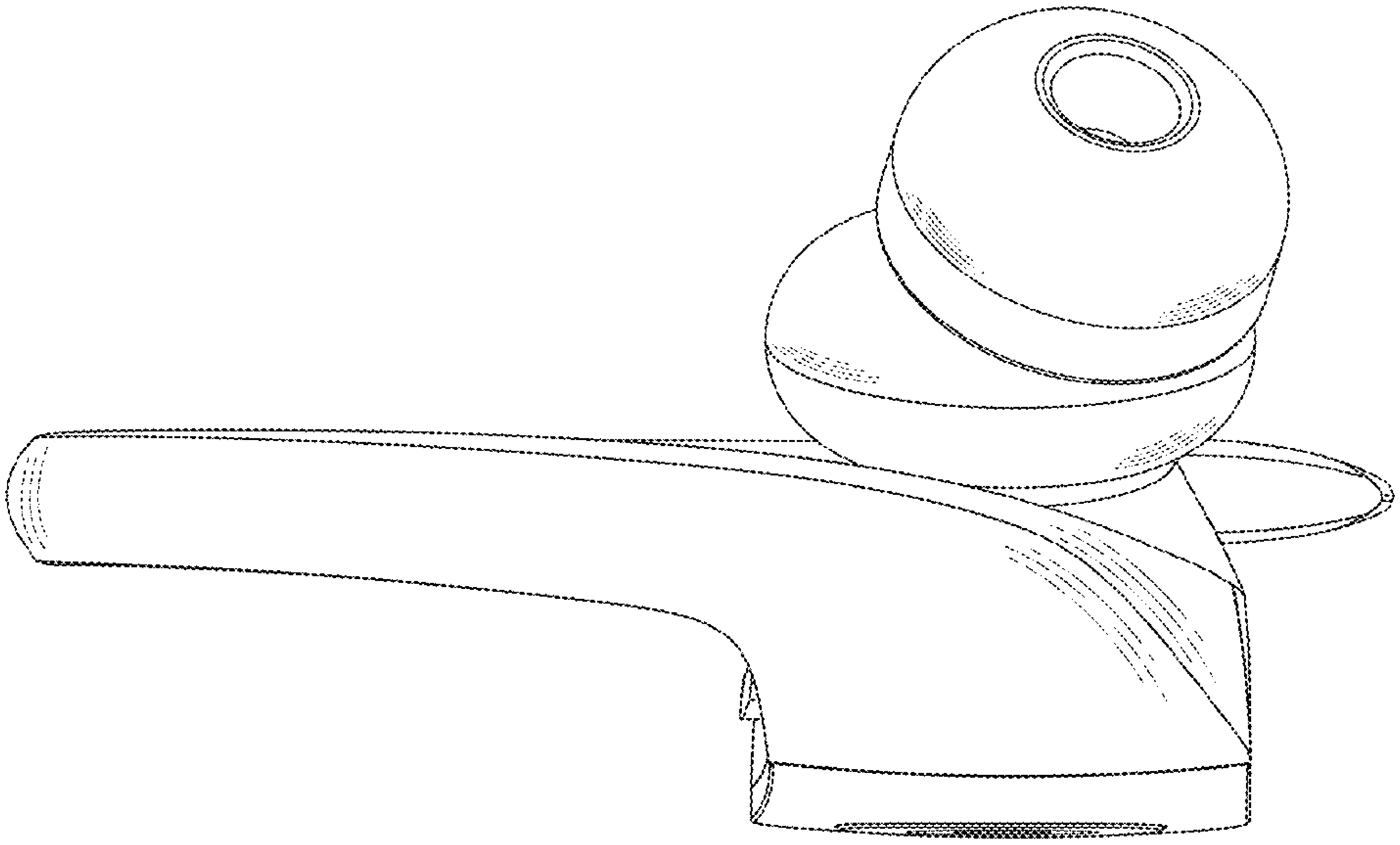

FIG. 7

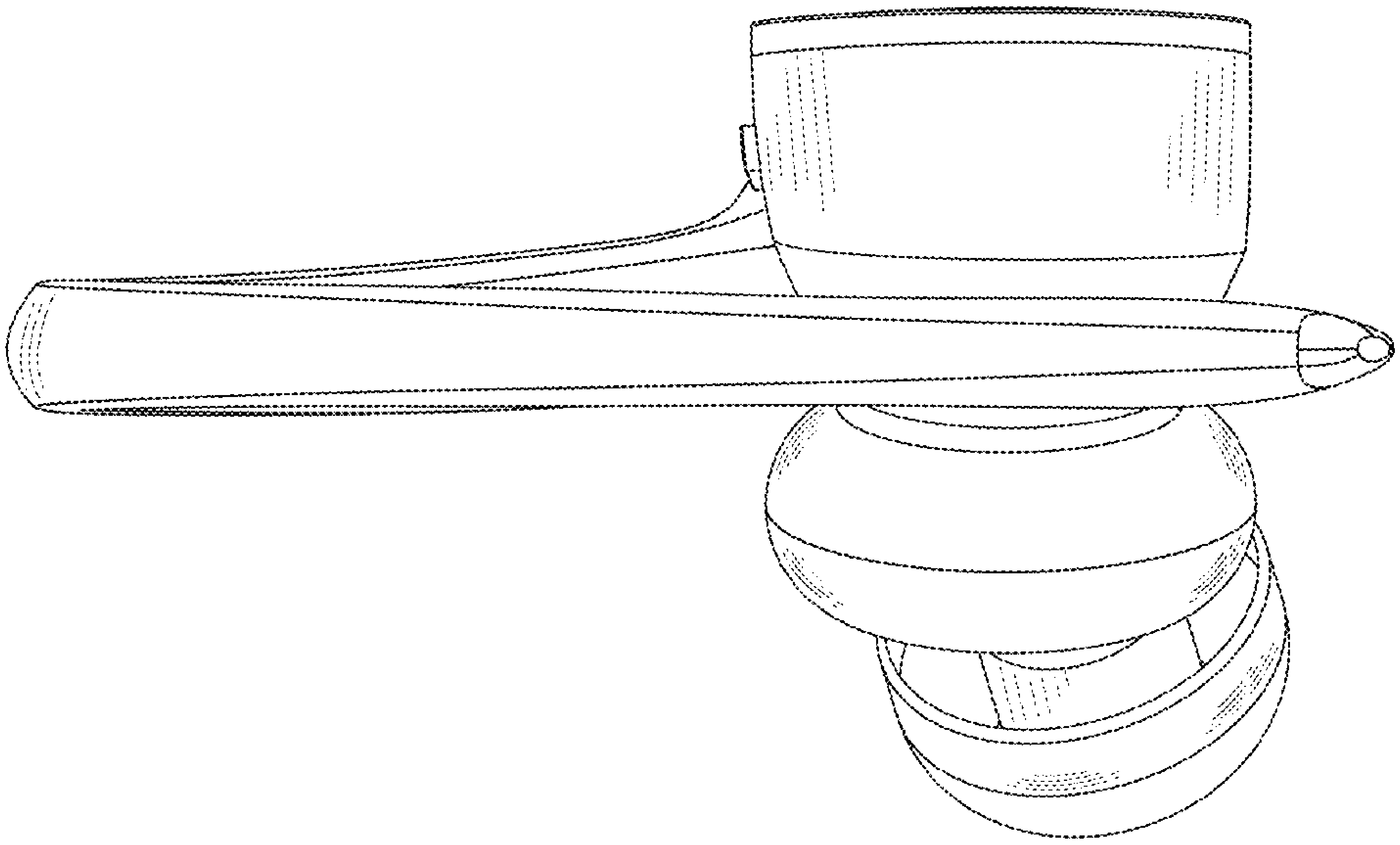

FIG. 8